mSATA
3TG6-P series

- SATA III solution for industrial field
- High IOPS
- iSMART disk health monitoring
- End to end data path protection
- iData Guard for abnormal power failure
- DEVSLP supported

Introduction

Innodisk mSATA 3TG6-P is SATA III 6Gb/s solid state disk, which delivers excellent performance, especially in random data transfer rate, and which offers reliability making it the ideal solution for a variety of applications, including embedded system, industrial computing, and enterprise field. 3TG6-P mSATA not only performs unmatched performance, but also designed with Innodisk owned technical knowhow to ensure the data integrity and highest levels of reliability.
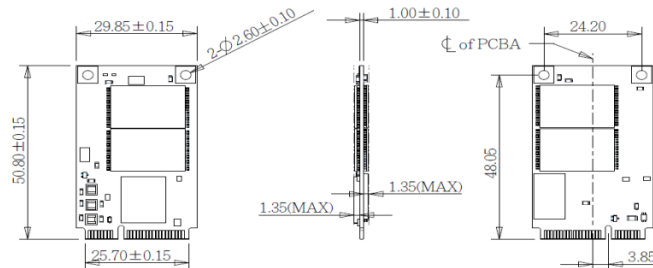
innodisk

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Drawing

Contact us for more information about the mSATA 3TG6-P

Innodisk is a service-driven provider of industrial embedded flash and DRAM storage products and technologies, with a focus on the industrial/embedded, aerospace and defense, and cloud computing industries.

TOLERENCE: ±0.15mm
UNIT: mm

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Specifications

Interface	SATA III
Flash Type	3D TLC
Capacity	128GB~2TB
Max. Channels	4
Sequential R/W (MB/sec, max.)*	560 / 520 MB/s
4KB Random (QD32) R/W (IOPS)*	87,000/ 75,000
Max. Power Consumption	4.8W (3.3V x 1.45 mA)
Thermal Sensor	√
External DRAM Buffer	√
AES encryption	optional
ATA Security	√
S.M.A.R.T.	√
DEVSLP Mode	√ (min. power consumption 3mW)
Dimension (WxLxH)	29.85 X 50.80 X 3.7 mm
Environment	Vibration: 20G @7~2000Hz Shock: 1500G @ 0.5ms Storage Temperature: -40°C ~ +85°C MTBF: 3 million hours

* Sequential performance based on CystalDiskMark 5.1.2 with file size 1000MB

Ordering Information (Please refer to TPS for detail)

Operation Temp.	128GB	256GB	512GB	1TB	2TB
Standard Grade (0°C ~ +70°C)	DGMSR-A28M71%C*QF	DGMSR-B56M71%C*QF	DGMSR-C12M71%C*QF	DGMSR-01TM71%C*QF	DGMSR-02TM71%CAQF
Industrial Grade (-40°C ~ +85°C)	DGMSR-A28M71%W*QF	DGMSR-B56M71%W*QF	DGMSR-C12M71%W*QF	DGMSR-01TM71%W*QF	DGMSR-02TM71%WAQF

%. E: 64 layers 3D TLC; G: 96 layers 3D TLC; K: 112 layers 3D TLC/ *. PCB version control